

EE105

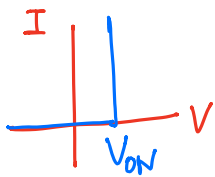
**Microelectronic Devices and Circuits:
P-N Junctions and Semiconductor Fabrication**

Prof. Ming C. Wu

wu@eecs.berkeley.edu

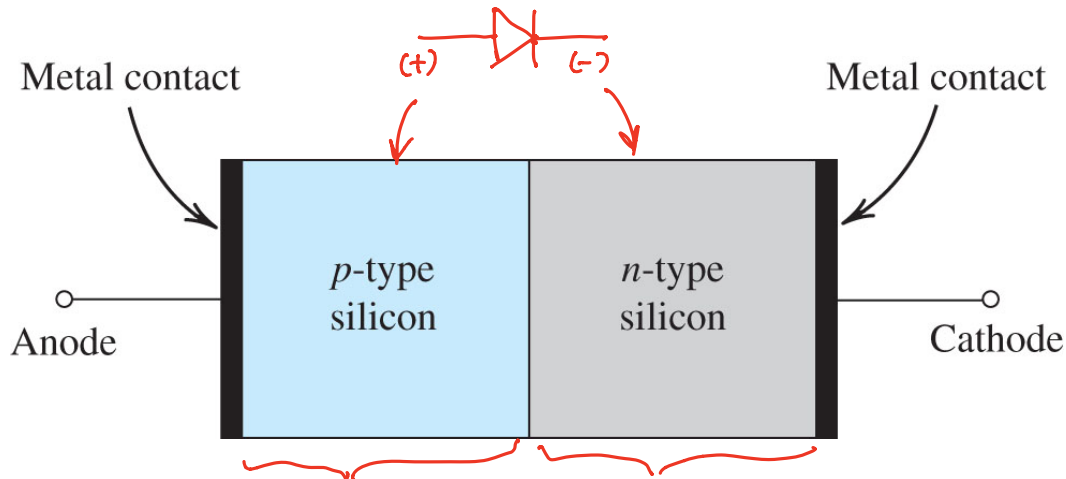
511 Sutardja Dai Hall (SDH)



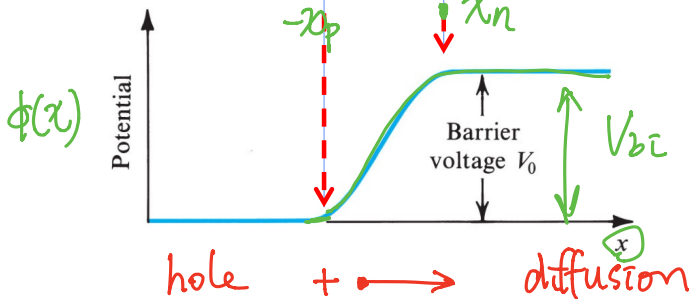
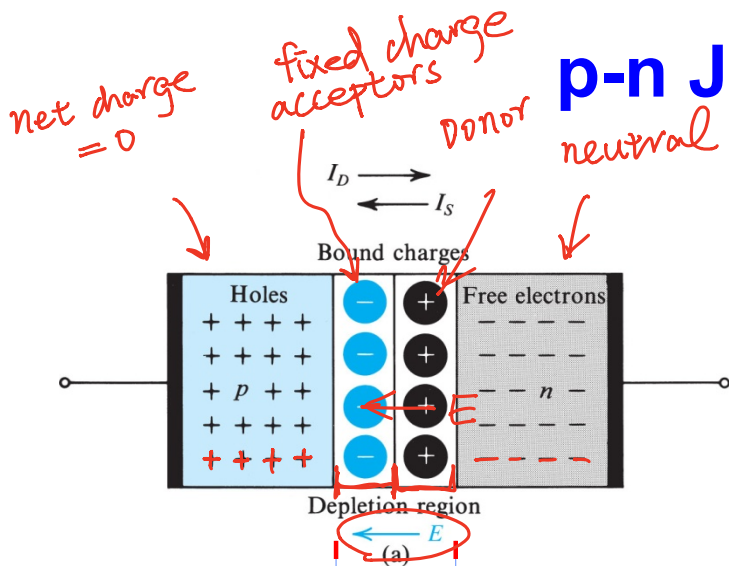


p-n Junction

- p-type semiconductor in contact with n-type
- Basic building blocks of semiconductor devices
 - Diodes,
 - Bipolar junction transistors (BJT),
 - Metal-oxide-semiconductor field effect transistors (MOSFET)



p-n Junction



hole + → diffusion
 electron ← -

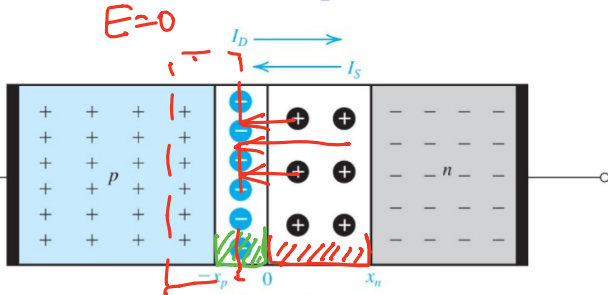
← E (< 0) ~
 hole + ←
 → - electron

- When p- and n-type semiconductors are “joined”
 - Holes near junction diffuse to n-side
 - Electrons near junction diffuse to p-side
- “Depletion region” formed near junction
 - No electrons, no holes
- A “built-in” potential is formed to oppose further movement of electrons and holes

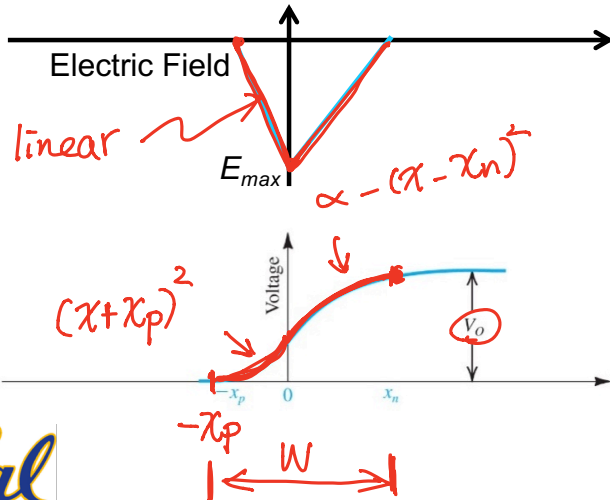
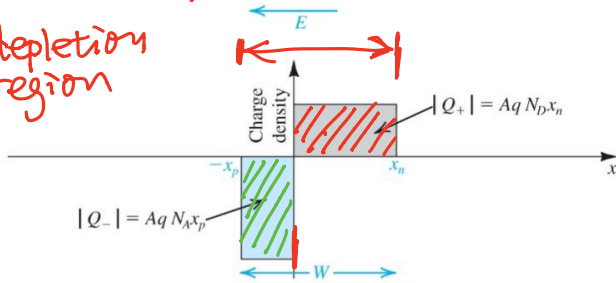
$$\phi = - \int_{-x_p}^{x_n} E(x) dx = V_{bi} > 0$$

$$E = - \frac{d\phi}{dx}$$

Simplified Analysis of p-n Junction



depletion region



Gauss Law:

$$\oint \vec{E} \cdot d\vec{A} = \frac{Q}{\epsilon_s}$$

Electrical potential:

$$V = - \int_{-\infty}^x E(x') dx'$$

$\int ax dx = \frac{1}{2} ax^2$

Built-in potential:

$$V_0 = V_T \cdot \ln \left(\frac{N_A N_D}{n_i^2} \right)$$

controlled by doping N_A, N_D

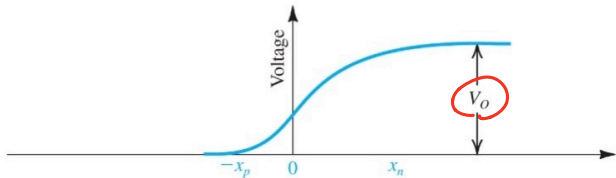
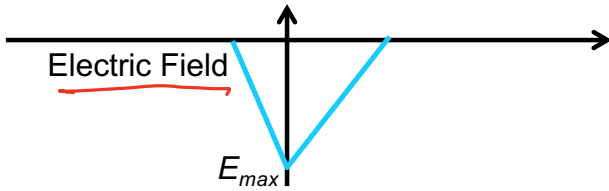
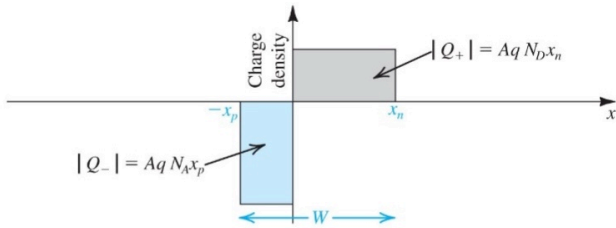
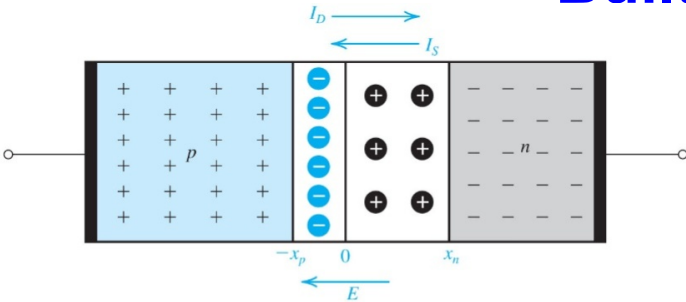
Depletion width:

$$W = \sqrt{\frac{2\epsilon_s}{q} \left(\frac{1}{N_A} + \frac{1}{N_D} \right) V_0}$$

$x_n + x_p$

high doping
 \Rightarrow large N_A, N_D
 \Rightarrow small W

Built-in Potential



Built-in potential:

$$V_0 = V_T \cdot \ln \left(\frac{N_A N_D}{n_i^2} \right)$$

$V_T = \frac{k_B T}{q}$: thermal voltage = 26 mV at room temperature

N_A : p-doping (Acceptor)

N_D : n-doping (Donor)

n_i : intrinsic carrier concentration

$n_i = 1.5 \times 10^{10} \text{ cm}^{-3}$ for Si

Alternative form:

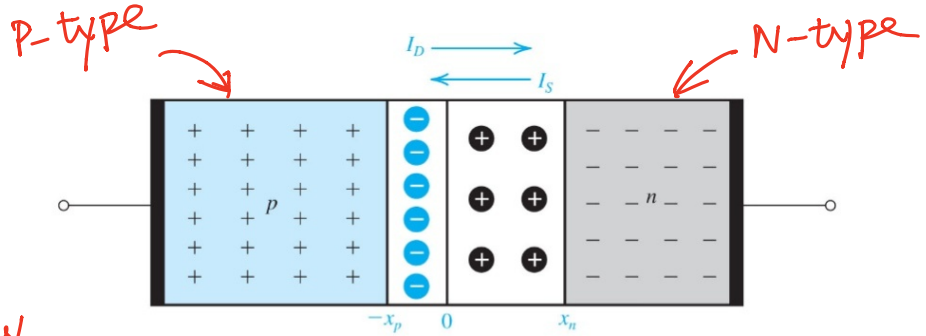
$$V_0 = \underbrace{60 \text{ mV}}_V \cdot \underbrace{\log}_{\ln 10} \left(\frac{N_A N_D}{n_i^2} \right)$$

Example:

$N_A = 1.5 \times 10^{17}$, $n_D = 1.5 \times 10^{18} \text{ [cm}^{-3}\text{]}$

$V_0 = 60 \text{ mV} \cdot \log(10^{15}) = 900 \text{ mV}$

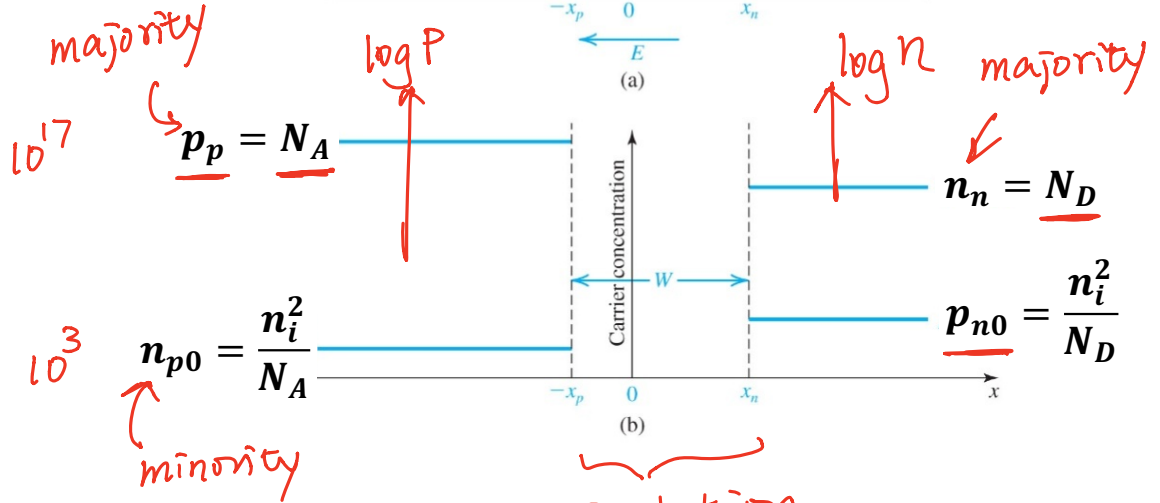
Carrier Concentration in p-n Junction



At equilibrium:

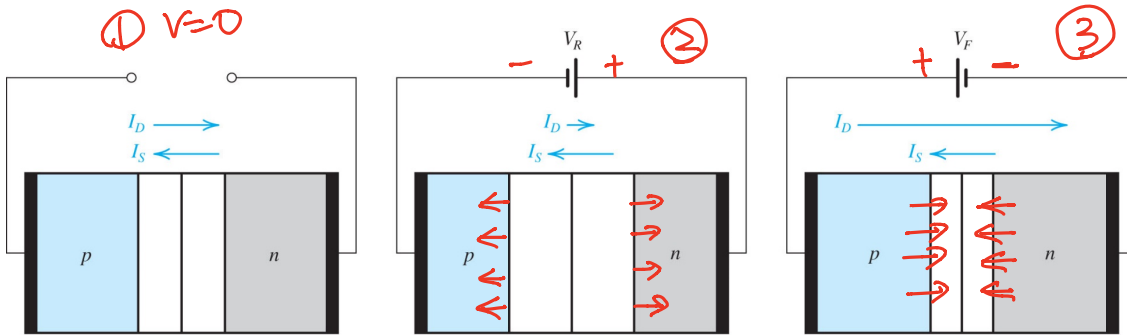
$$\underline{n \times p = n_i^2}$$

↑
Mass Action Law

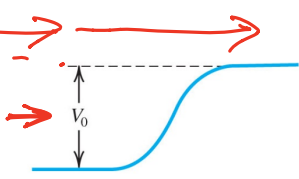


Depletion
 → No holes
 → No electrons

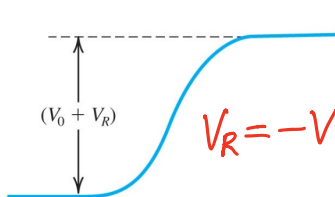
Depletion Width Under Bias



$P(x)$
 $P = P_0 e^{\frac{q\phi}{k_B T}}$

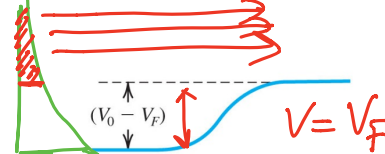


Open circuit
 $(V = 0)$
Equilibrium



Reverse Bias
 $(V < 0)$

- **Larger barrier**
- **Wider depletion**



Forward Bias
 $(V > 0)$

- **Smaller barrier**
- **Narrower depletion**

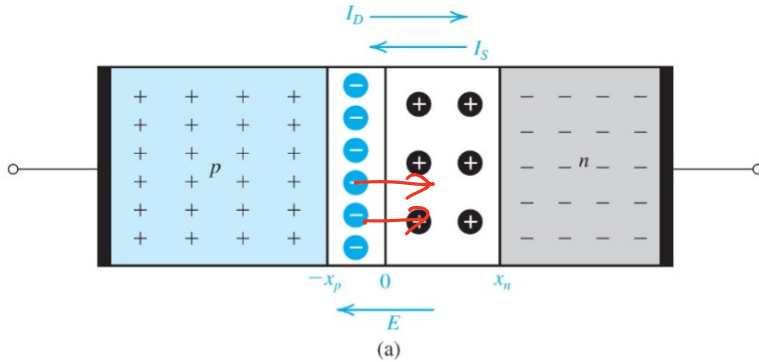
$\rightarrow J$

$$W = \sqrt{\frac{2\epsilon_s}{q} \left(\frac{1}{N_A} + \frac{1}{N_D} \right) (V_0 - V)}$$

← applied voltage
 ③ $V > 0$ = forward bias
 ② $V < 0$ = reversed bias

① $V=0$

Extra Holes in N Side Under Forward Bias



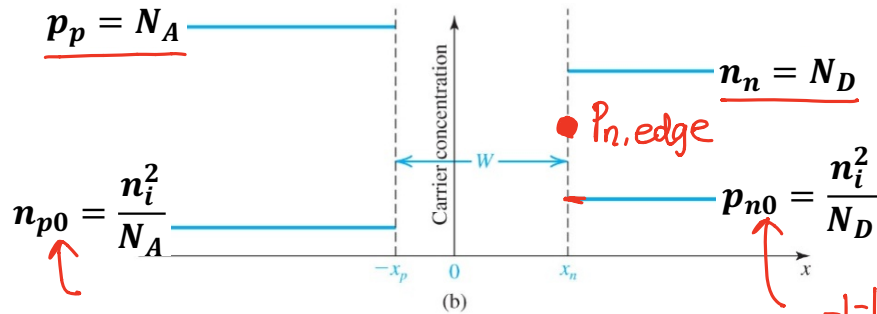
Excess holes in n-doped side:

$$\underline{p_{n,edge}} = \underline{p_{n0}} \cdot \left(e^{V/V_T} - 1 \right)$$

$$e^{\frac{qV}{k_B T}} = e^{\frac{V}{V_T}}$$

$$V_T = \frac{k_B T}{q}$$

Forward Bias
Barrier lowered
by V

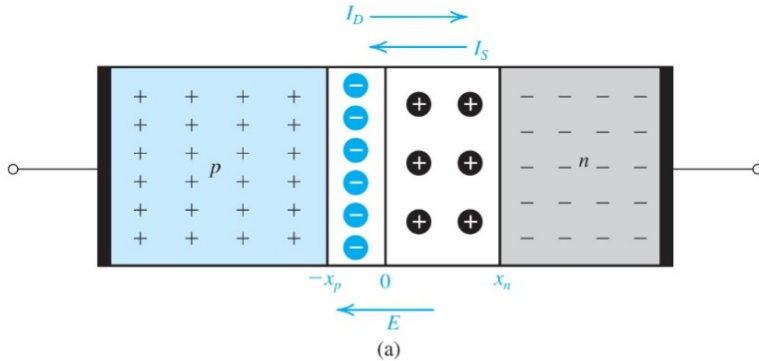


equilibrium

Boltzmann Dist

$$P = P_0 e^{\frac{-qV}{k_B T}}$$

Holes Recombine with Electrons on N Side

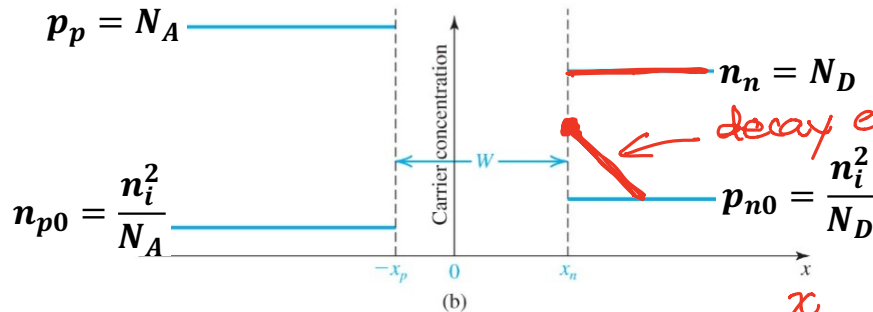


Excess holes in n-doped side:

$$\underline{p_{n,edge}} = p_{n0} \cdot (e^{V/V_T} - 1)$$

Excess holes recombines within diffusion length, L_p :

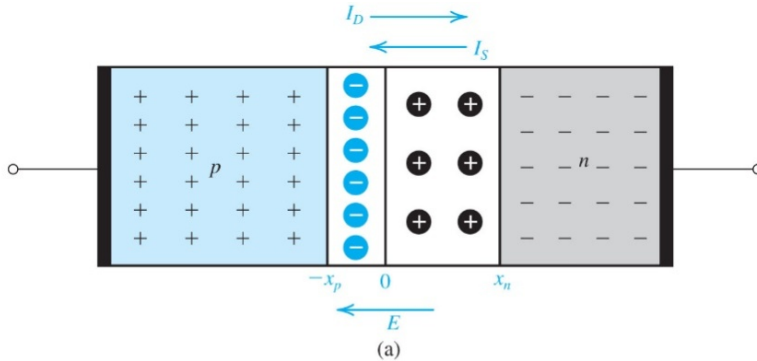
$$\frac{dp_n(x)}{dx} = -\frac{p_{n,edge}}{L_p}$$



$$\Delta p \propto e^{-\frac{x}{L_p}} = L_p = \text{diffusion length}$$

$$\frac{dP_n(x)}{dx} = -\frac{1}{L_p} P_n(x)$$

Diffusion Currents Under Forward Bias



Excess holes in n-doped side:

$$p_{n,edge} = p_{n0} \cdot (e^{V/V_T} - 1)$$

Excess holes recombines within diffusion length, L_p :

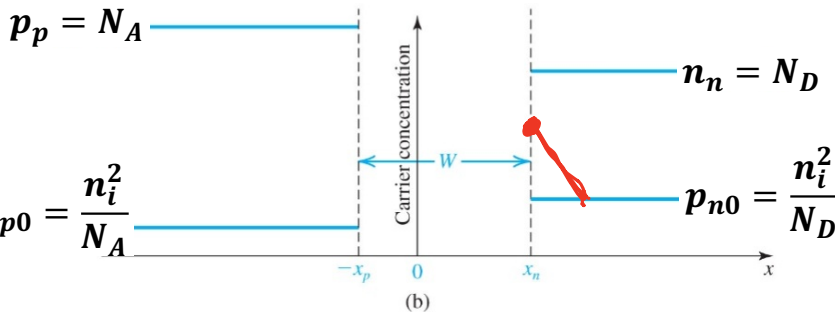
$$\frac{dp_n(x)}{dx} = \frac{-p_{n,edge}}{L_p}$$

Diffusion current:

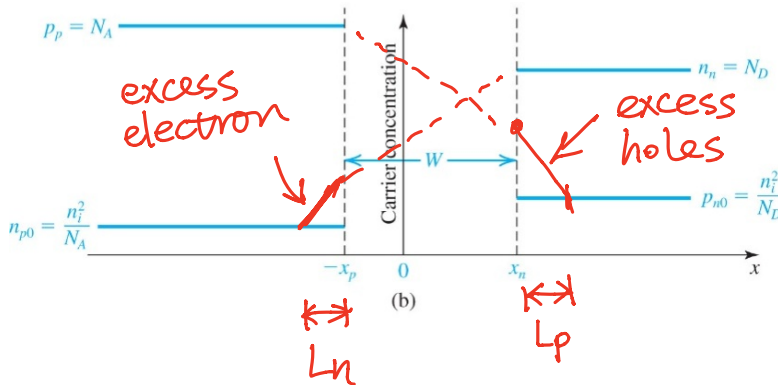
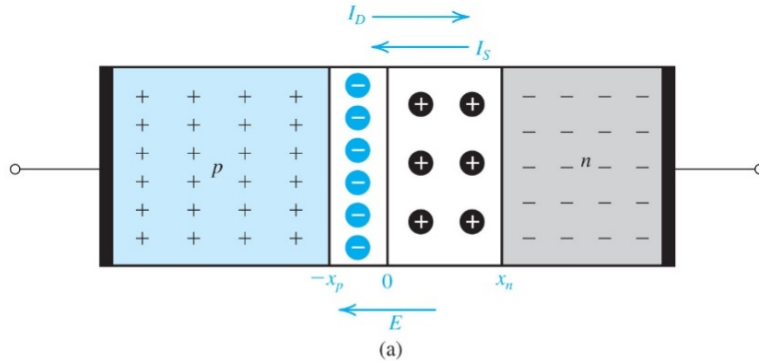
$$J_p = -qD_p \frac{dp_n(x)}{dx}$$

$$= \frac{qD_p}{L_p} p_{n0} \cdot (e^{V/V_T} - 1)$$

$$\rightarrow J_p \propto (e^{\frac{V}{V_T}} - 1)$$



Total Currents Under Forward Bias



Hole Diffusion current on N-side

$$J_p = \frac{qD_p}{L_p} p_{n0} \cdot (e^{V/V_T} - 1)$$

Similarly,

Electron Diffusion current on P-side

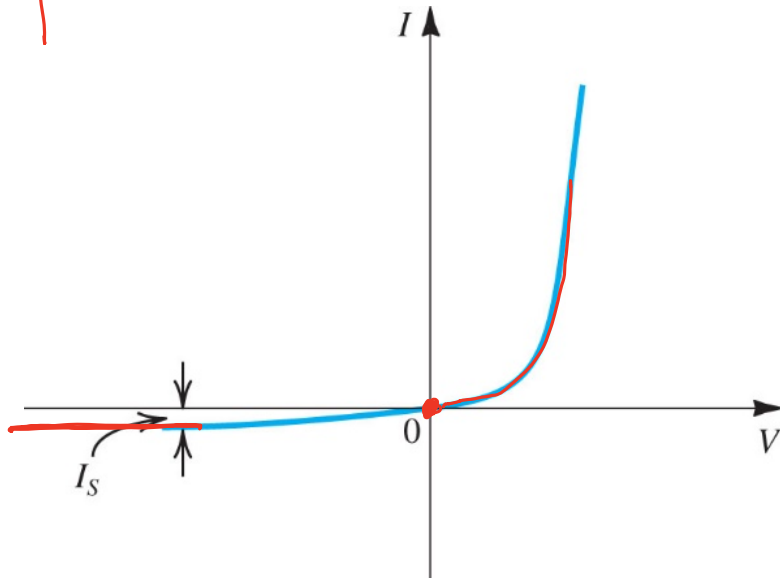
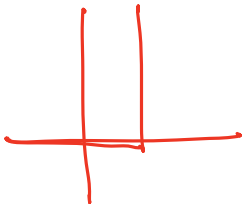
$$J_n = \frac{qD_n}{L_n} n_{p0} \cdot (e^{V/V_T} - 1)$$

Total current

$$I = \text{Area} \cdot (J_p + J_n) \propto (e^{V/V_T} - 1)$$

[Amp]

I-V Curve



$$\begin{aligned}
 V < 0 \\
 e^{\frac{V}{V_T}} &\ll 1 \\
 I &= I_s (0 - 1) \\
 &= -I_s
 \end{aligned}$$

$$\begin{aligned}
 V = 0 & \quad V > 0 \\
 I = 0 & \quad e^{\frac{V}{V_T}} \gg 1 \\
 I &= I_s e^{\frac{V}{V_T}}
 \end{aligned}$$

$$I = I_s (e^{V/V_T} - 1)$$

where

$$I_s = Aqn_i^2 \left(\frac{D_p}{L_p N_D} + \frac{D_n}{L_n N_A} \right)$$

Reverse saturation current

$$I_s \sim 10^{-15} \text{ Amp}$$

$$e^{\frac{V}{V_T}} \quad V = 0.8 \text{ V} = 800 \text{ mV}$$

$$\parallel e^{\frac{800}{25}} = e^{32} \approx 10^{16}$$

Capacitance in p-n Junction: Depletion Capacitance

Parallel plate capacitance:

$$C_j = \frac{\epsilon_s A}{W} \leftarrow W(V_R)$$

Plate separation, W , is voltage dependent:

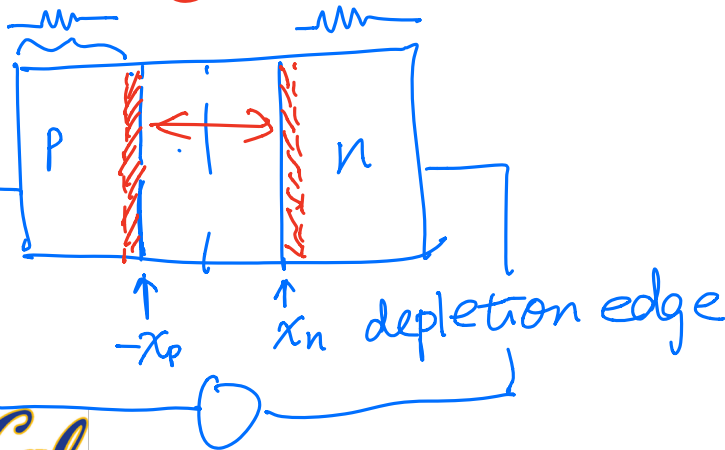
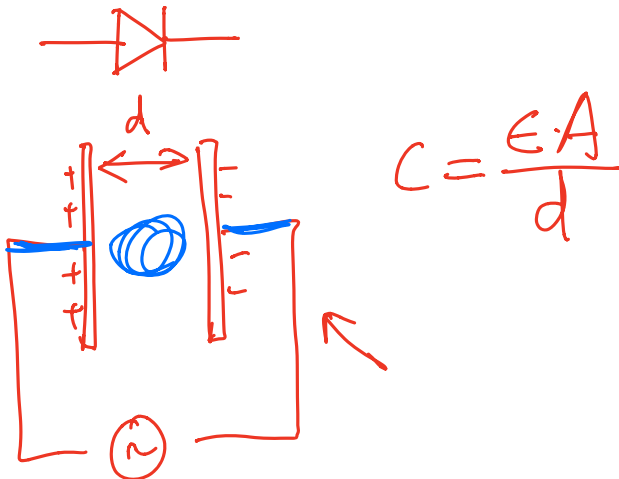
$$W = \sqrt{\frac{2\epsilon_s}{q} \left(\frac{1}{N_A} + \frac{1}{N_D} \right) (V_0 + |V_R|)}$$

Variable capacitance:

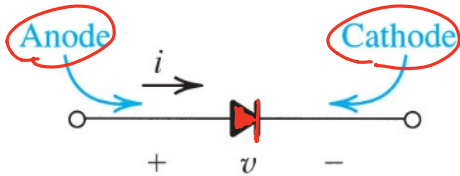
$$V_0 - V = V_0 - (-|V_R|)$$

$$C_j(V_R) = \frac{C_{j0}}{\sqrt{1 + \frac{|V_R|}{V_0}}}$$

$$C_{j0} = \frac{\epsilon_s A}{W(V_R=0)}$$



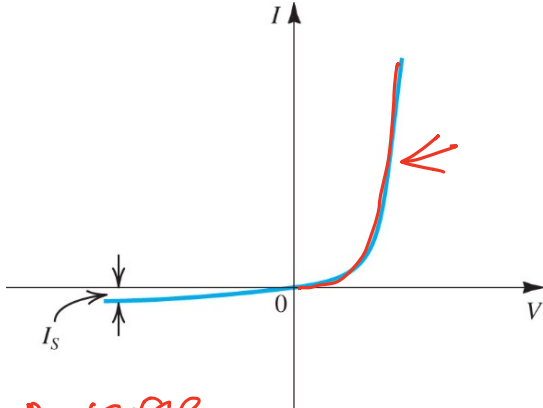
Summary of p-n Junction



Built-in potential : $V_0 = V_T \ln \left(\frac{N_A N_D}{n_i^2} \right)$

I-V curve :

$$I = I_S \left(e^{V/V_T} - 1 \right)$$



Reverse

$$I = -I_S$$

Variable
Cap

Capacitance : $C_j = \frac{C_{j0}}{\sqrt{1 + \frac{|V_R|}{V_0}}}$

Depletion Width: $W = \sqrt{\frac{2\epsilon_s}{q} \left(\frac{1}{N_A} + \frac{1}{N_D} \right) (V_0 - V)}$